

Global Thin Wafers Temporary Bonding Equipment and Materials Market Growth (Status and Outlook) 2025-2031

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Abstracts

According to this study, the global Thin Wafers Temporary Bonding Equipment and Materials market size will reach US\$ million by 2031.

Thin wafer handling will enjoy increased importance in the coming years, but as chips get thinner and wafer diameter increases, thinning/handling procedures are required. This implies development in wafer thinning, wafer dicing and wafer temporary bonding. Temporary bonding implies know-how in process and chemistry, and an understanding of the final application requirements. Temporary bonding is a complex technology, requiring an interface material (sometimes called the “Magic” material) that is strong enough to withstand post-processing but which can be easily removed afterwards. As the main concern for temporary bonding materials (wax, tape or glue) is temperature stability, the material must be strong enough to withstand processing steps (metallization, etching, grinding). Another issue is the choice of carrier material. Carrier lifetime depends on its capability to withstand steps such as grinding, etc., and carrier lifetime should be at least tens of times.

According to our Semiconductor Research Center, in 2022, the global semiconductor equipment was valued at US\$ 109 billion. China mainland, China Taiwan and South Korea have a combined market share over 70%. North America, Europe and Japan, have a combined market share of 23%. The key drivers are high performance computing, AI, cloud computing, Servers, 5G and EV (electric vehicle), etc.

LPI (LP Information)' newest research report, the “Thin Wafers Temporary Bonding Equipment and Materials Industry Forecast” looks at past sales and reviews total world Thin Wafers Temporary Bonding Equipment and Materials sales in 2024, providing a

comprehensive analysis by region and market sector of projected Thin Wafers Temporary Bonding Equipment and Materials sales for 2025 through 2031. With Thin Wafers Temporary Bonding Equipment and Materials sales broken down by region, market sector and sub-sector, this report provides a detailed analysis in US\$ millions of the world Thin Wafers Temporary Bonding Equipment and Materials industry.

This Insight Report provides a comprehensive analysis of the global Thin Wafers Temporary Bonding Equipment and Materials landscape and highlights key trends related to product segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyses the strategies of leading global companies with a focus on Thin Wafers Temporary Bonding Equipment and Materials portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms' unique position in an accelerating global Thin Wafers Temporary Bonding Equipment and Materials market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for Thin Wafers Temporary Bonding Equipment and Materials and breaks down the forecast by Type, by Application, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast offers a highly nuanced view of the current state and future trajectory in the global Thin Wafers Temporary Bonding Equipment and Materials.

This report presents a comprehensive overview, market shares, and growth opportunities of Thin Wafers Temporary Bonding Equipment and Materials market by product type, application, key players and key regions and countries.

Segmentation by Type:

Chemical Debonding

Hot Sliding Debonding

Mechanical Debonding

Laser Debonding

Segmentation by Application:

below 40µm Wafers

This report also splits the market by region:

Americas

United States

Canada

Mexico

Brazil

APAC

China

Japan

Korea

Southeast Asia

India

Australia

Europe

Germany

France

UK

Italy

Russia

Middle East & Africa

Egypt

South Africa

Israel

Turkey

GCC Countries

The below companies that are profiled have been selected based on inputs gathered from primary experts and analyzing the company's coverage, product portfolio, its market penetration.

3M

ABB

Accretech

AGC

AMD

Cabot

Corning

Crystal Solar

Dalsa

DoubleCheck Semiconductors

1366 Technologies

Ebara

ERS

Hamamatsu

IBM

Intel

LG Innotek

Mitsubishi Electric

Qualcomm

Robert Bosch

Samsung

Sumitomo Chemical

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